Materials Declaration

Package	MQFP
Body Size	28 X 28
LeadCount	128
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	2.72 E-01	51036
SiO2 Filler	86	2.93 E+00	548637
Phenol Resin	5	1.70 E-01	31897
Antimony_Sb2O3	0.4	1.36 E-02	2552
Brominated Resin	0.4	1.36 E-02	2552
Carbon Black	0.2	6.81 E-03	1276

Molding Compound

Item	PPM	Method
Pb	4.90	EPA method #3052 (ICP-AES)
Cd	<2.0	BS EN 1122:2001B (ICP-AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS In-House Method
PBDE	ND	SGS In-House Method

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.02 E+00	191549
Ni	3	3.19 E-02	5973
Si	0.65	6.91 E-03	1294
Mg	0.15	1.59 E-03	299

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	2.0	EPA method 7196A & EPA 3060A

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	3.60 E-02	6745

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	1.98 E-02	3711

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.96 E-03	742

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	7.53 E-01	141105

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	23	1.31 E-02	2445
Ag Filler	77	4.37 E-02	8186

Package Totals

Weight (g)	PPM
5.34 E+00	1000000

STS-S-B

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

6/11/04

ANALOG DEVICES

ADI Proprietary

Materials Declaration

Package	MQFP
Body Size	28 X 28
LeadCount	128
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Epoxy resin	8	2.72 E-01	51036
SiO2 Filler	86	2.93 E+00	548637
Phenol Resin	5	1.70 E-01	31897
Antimony_Sb2O3	0.4	1.36 E-02	2552
Brominated Resin	0.4	1.36 E-02	2552
Carbon Black	0.2	6.81 E-03	1276

Molding Compound

Item	PPM	Method
Pb	4.90	EPA method #3052 (ICP-AES)
Cd	<2.0	BS EN 1122:2001B (ICP-AES)
Hg	<2.0	Mercury Analyser
Cr+6	<2.0	EPA method #3060A(UV)
PBB	ND	SGS In-House Method
PBDE	ND	SGS In-House Method

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	1.02 E+00	191549
Ni	3	3.19 E-02	5973
Si	0.65	6.91 E-03	1294
Mg	0.15	1.59 E-03	299

Die Attach Paste

Item	PPM	Method
Pb	<5.0	ICP-AES
Cd	<5.0	ICP-AES
Hg	<5.0	ICP-AES
Cr+6	2.0	EPA method 7196A & EPA 3060A

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100	3.60 E-02	6745

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	1.68 E-02	3155
Pb	15	2.97 E-03	557

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	3.96 E-03	742

Chip

	% of Chip	Weight (g)	PPM
Si	**100**	7.53 E-01	141105

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	23	1.31 E-02	2445
Ag Filler	77	4.37 E-02	8186

Package Totals

Weight (g)	PPM
5.34 E+00	1000000

STS-S-A

Note: The information provided in this declaration are true to the best of ADI's knowledge.
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6/11/04